



**(43) International Publication Date**  
**24 March 2005 (24.03.2005)**

**PCT**

**(10) International Publication Number**  
**WO 2005/025804 A1**

- (51) **International Patent Classification<sup>7</sup>:** B24B 37/04, 49/12

(21) **International Application Number:** PCT/JP2004/008787

(22) **International Filing Date:** 16 June 2004 (16.06.2004)

(25) **Filing Language:** English

(26) **Publication Language:** English

(30) **Priority Data:**  
2003-318307 10 September 2003 (10.09.2003) JP

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(81) **Designated States (unless otherwise indicated, for every kind of national protection available):** AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

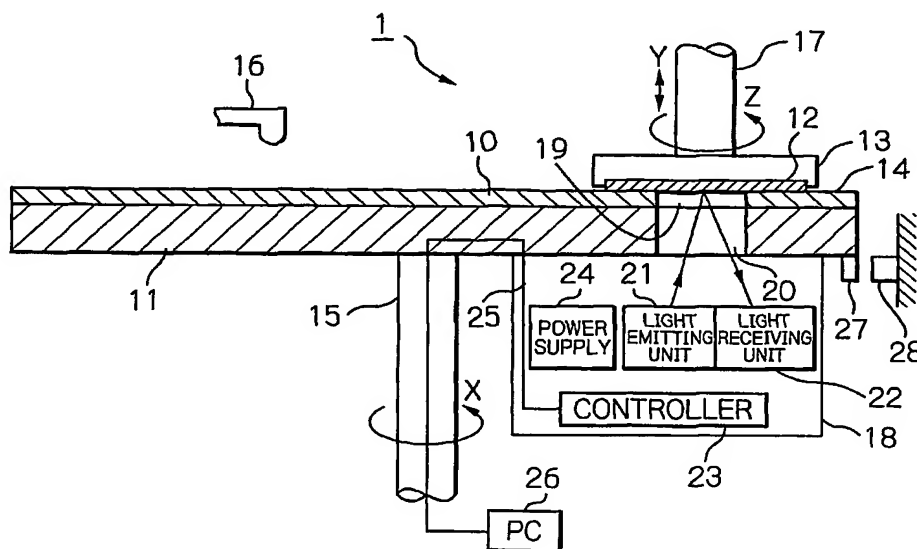
(84) **Designated States (unless otherwise indicated, for every kind of regional protection available):** ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

**Published:**  
— with international search report

**Published:**  
— *with international search report*

[Continued on next page]

- (54) Title:** POLISHED STATE MONITORING APPARATUS AND POLISHING APPARATUS USING THE SAME



- (S7) Abstract:** A polished state monitoring apparatus capable of easily grasping the progress of polish is provided. The polished state monitoring apparatus monitors the progress of polish of a surface to be polished by obtaining a characteristic value indicating a state of the polished surface of an object 12 at each sampling point every predetermined interval while scanning the surface. The apparatus comprises light emitting means 21 capable of emitting light for irradiating the surface and computing units 26 for receiving light reflected from the surface to generate a characteristic value. Then, the apparatus fetches the characteristic values obtained from the sampling points at the same sampling timing during each scan and outputs the characteristic values. This enables the progress of the polish to be monitored in accordance with the distance from the center of the surface.



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*For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.*